

March 2008

FDA8440

N-Channel PowerTrench[®] MOSFET 40V, 100A, 2.1m Ω

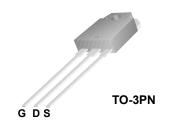
Features

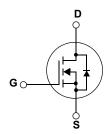
- $R_{DS(on)}$ = 1.46m Ω (Typ.)@ V_{GS} = 10V, I_D = 80A
- $Q_{g(tot)} = 345nC (Typ.)@V_{GS} = 10V$
- · Low Miller Charge
- · Low QRR Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- 160A Guarantee for 2 sec
- RoHS Compliant



Application

- · Automotive Engine Control
- · Powertrain Management
- · Motors, Solenoids
- · Electronic Steering
- · Integrated Starter/ Alternator
- · Distributed Power Architectures and VRMs
- · Primary Switch for 12V systems





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V _{DSS}	Drain to Source Voltage	40	V	
V _{GSS}	Gate to Source Voltage	±20	V	
I _D	Drain Current - Continuous (T _C = 155°C)	100	А	
	- Continuous (T_A = 25°C, V_{GS} = 10V, $R_{\theta JA}$ = 40°C/W)	30	А	
	- Pulsed	500	Α	
E _{AS}	Single Pulsed Avalanche Energy (Note 1)	1682	mJ	
D	Power dissipation	306	W	
P_{D}	Derate above 25°C	2.04	W/°C	
$T_{J_i} T_{STG}$	Operating and Storage Temperature	-55 to +175	οС	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.49	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 2	40	°C/W

Package Marking and Ordering Information

Device Marking Device		Package	Reel Size	Tape Width	Quantity
FDA8440	FDA8440	TO-3PN	N/A	N/A	30units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Conditio	Min	Тур	Max	Units	
Off Charac	teristics	-					
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$		40			V
I _{DSS}	7 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	V _{DS} = 32V				1	μΑ
	Zero Gate Voltage Drain Current	V _{GS} = 0V	$T_{\rm C} = 150^{\rm o}{\rm C}$			250	μΑ
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20V	1 -			±100	nA
On Charac	teristics			ı			
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		1		3	V
` '		V _{GS} = 4.5V, I _D = 80A			1.56	2.2	. mΩ
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 80A			1.46	2.1	
		$V_{GS} = 10V, I_D = 80A,$ $T_C = 175^{\circ}C$			2.82	4.1	
Dynamic C	haracteristics			ı			
C _{iss}	Input Capacitance				18600	24740	pF
C _{oss}	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz			1840	2450	pF
C _{rss}	Reverse Transfer Capacitance				1400	2100	pF
R _G	Gate Resistance	V _{GS} = 0.5V, f = 1MHz			1.1		Ω
Q _{g(tot)}	Total Gate Charge at 10V	V _{GS} = 0V to 10V			345	450	nC
Q _{g(2)}	Threshold Gate Charge	V _{GS} = 0V to 2V	V _{DD} = 20V		32.5		nC
Q _{gs}	Gate to Source Gate Charge		I _D = 80A		49		nC
Q _{gs2}	Gate Charge Threshold to Plateau		I _g = 1.0mA		16.5		nC
Q _{gd}	Gate to Drain "Miller" Charge	7			74		nC
Switching	Characteristics (V _{GS} = 10V)	•			•		
t _{ON}	Turn-On Time				175	360	ns
t _{d(on)}	Turn-On Delay Time	001/1 004			43	95	ns
t _r	Rise Time	$V_{DD} = 20V, I_D = 80A$ $V_{GS} = 10V, R_{GEN} = 7\Omega$	$V_{DD} = 20V, I_D = 80A$ $V_{CC} = 10V, R_{CCN} = 70$		130	275	ns
t _{d(off)}	Turn-Off Delay Time	- VGS 10V, NGEN 122			435	875	ns
t _f	Fall Time				290	590	ns
t _{OFF}	Turn-Off Time				730	1470	ns
Drain-Sour	rce Diode Characteristics and Maximu	ım Ratings		1	1		
V _{SD}	Source to Drain Diode Voltage	I _{SD} = 80A				1.25	V
		I _{SD} = 40A				1.0	V
t _{rr}	Reverse Recovery Time	I _{SD} = 75A, dI _{SD} /dt = 100A/μs			59		ns
Q _{RR}	Reverse Recovery Charge	I _{SD} = 75A, dI _{SD} /dt = 10	0A/μs		77		nC

NOTES:

^{1:} Starting T $_{J}$ = 25°C, L = 1mH, I $_{AS}$ = 58A, V $_{DD}$ = 36V, V $_{GS}$ = 10V.

^{2:} Pulse width = 100s

Typical Performance Characteristics

Figure 1. On-Region Characteristics

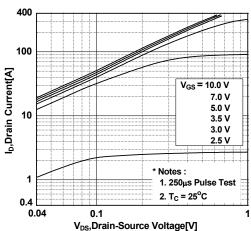


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

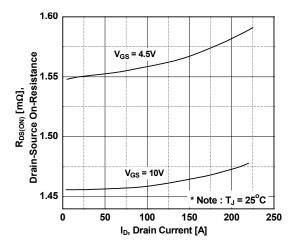


Figure 5. Capacitance Characteristics

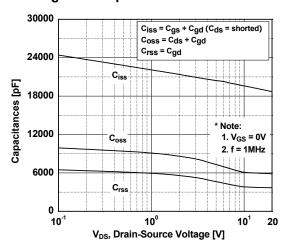


Figure 2. Transfer Characteristics

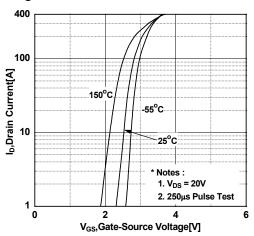


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

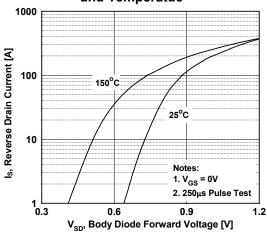
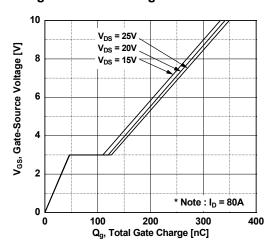


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

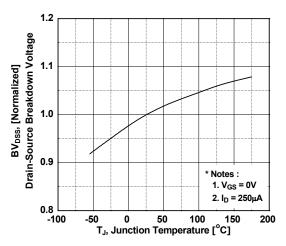


Figure 9. Unclamped Inductive Switching Capability

Figure 8. On-Resistance Variation vs. Temperature

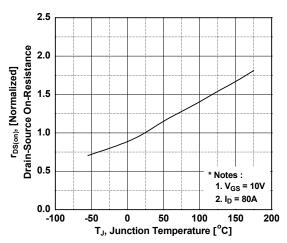
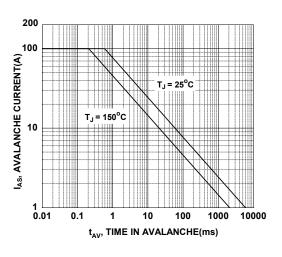


Figure 10. Safe Operating Area



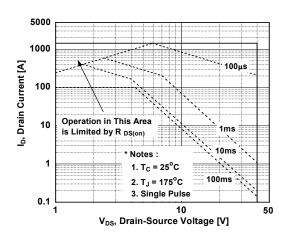
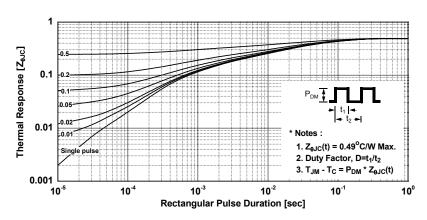
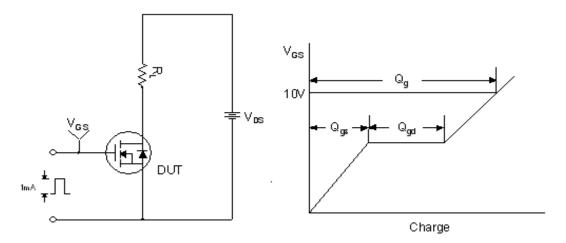


Figure 11. Transient Thermal Response Curve

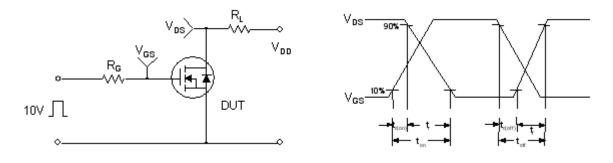


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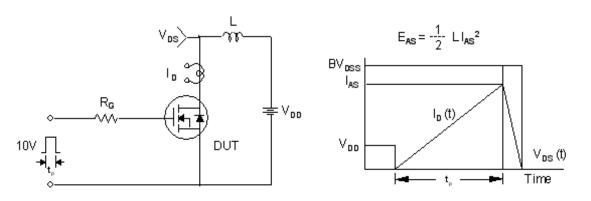
Gate Charge Test Circuit & Waveform



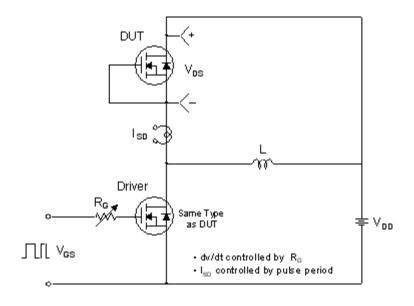
Resistive Switching Test Circuit & Waveforms

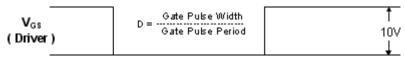


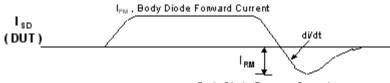
Unclamped Inductive Switching Test Circuit & Waveforms

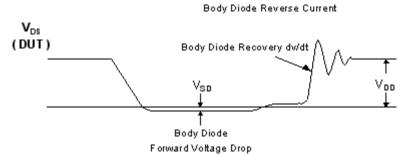


Peak Diode Recovery dv/dt Test Circuit & Waveforms



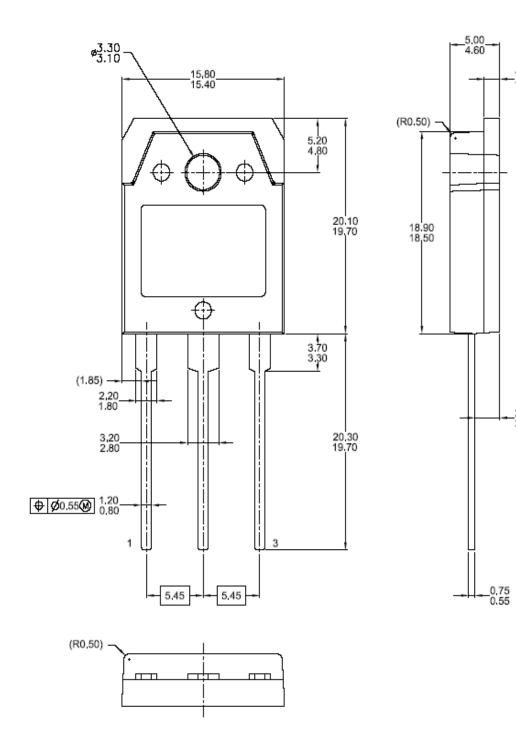






Mechanical Dimensions

TO-3PN



Dimensions in Millimeters





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